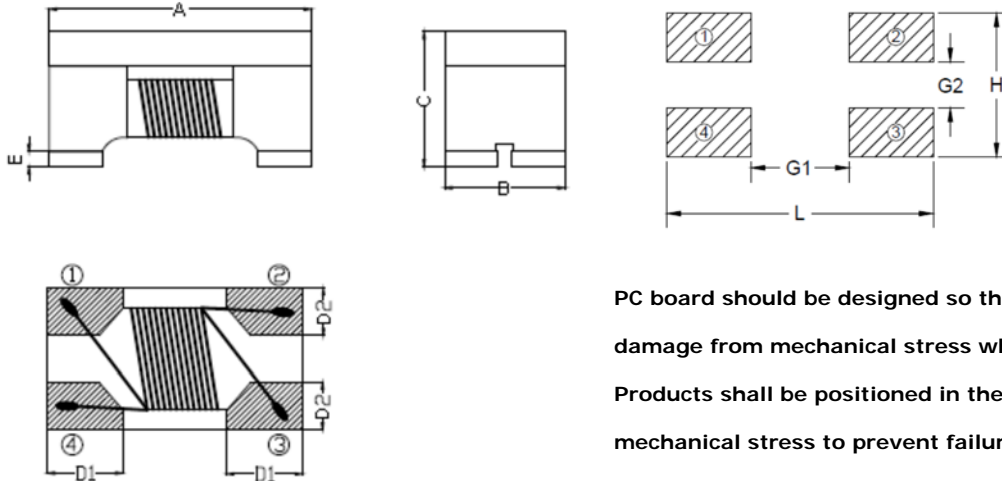


## FEATRLRES

- High common mode impedance at high frequency cause excellent noise suppression performance.
- 100% Lead(Pb) & Halogen-Free and RoHS compliant.

## CONFIGLRATIONS & DIMENSIONS ( unit in mm )

### Recommended PC Board Pattern



PC board should be designed so that products can prevent damage from mechanical stress when warping the board.

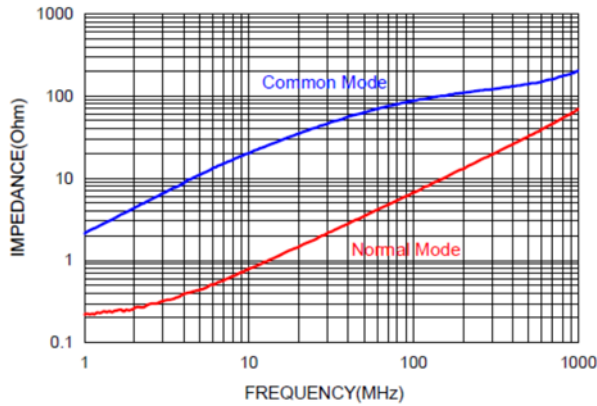
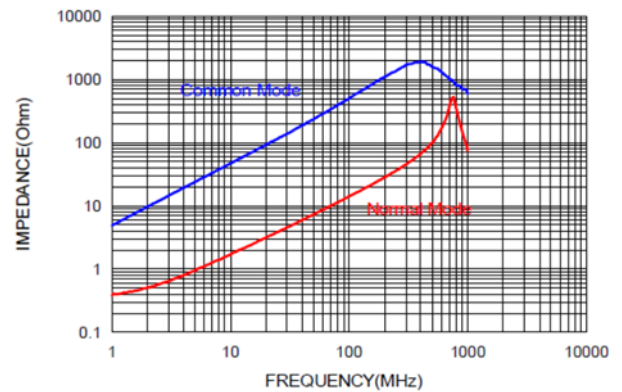
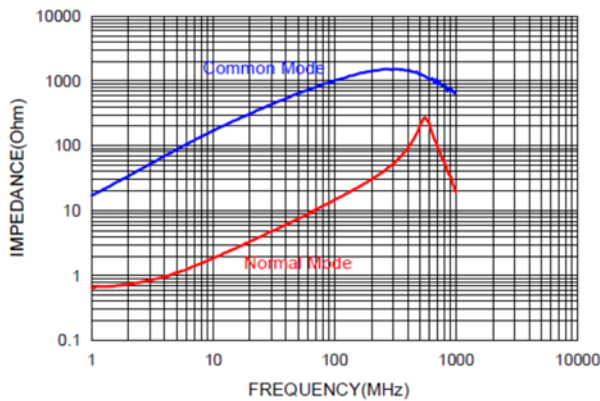
Products shall be positioned in the sideways direction against the mechanical stress to prevent failure.

Series	A	B	C	D1	D2	E	G1	G2	H	L
3225F2SF	3.2±0.2	2.5±0.2	2.2±0.2	0.8±0.1	0.9±0.1	0.15±0.1	1.6	0.6	3.5	4.4

## ELECTRICAL CHARACTERISTICS

Part Number	Impedance ( $\Omega$ )	Test Frequency (MHz)	DC Resistance ( $\Omega$ ) max.	Rated Current (mA)max.	Rated Volt. (Vdc)max.	Withstand Volt. (Vdc) max.	IR ( $\Omega$ ) min.
WCM3225F2SF-900T10	90±25%	100	0.050	1000	50	125	10M
WCM3225F2SF-601T10	600±25%	100	0.20	1000	50	125	10M
WCM3225F2SF-102T04	1000±25%	100	0.30	400	50	125	10M

## Typical Impedance v.s. Frequency Curve

**WCM3225F2SF-900**

**WCM3225F2SF-601**

**WCM3225F2SF-102**


## Reliability and Test Condition

Item	Performance	Test Condition
Operating temperature	-40~+125°C (Including self - temperature rise)	
Storage temperature	1. -10~+40°C ,50~60%RH (Product with taping) 2. -40~+125°C (on board)	
<b>Electrical Performance Test</b>		
Inductance	Refer to standard electrical characteristics list.	HP4284A,CH11025,CH3302,CH1320,CH1320S LCR Meter.
DCR		CH16502,Agilent33420A Micro-Ohm Meter.
Saturation Current (Isat)	Approximately $\Delta$ L30%	Saturation DC Current (Isat) will cause L0 to drop $\Delta$ L(%)
Heat Rated Current (Irms)	Approximately $\Delta$ T40°C	Heat Rated Current (Irms) will cause the coil temperature rise $\Delta$ T(°C). 1. Applied the allowed DC current 2. Temperature measured by digital surface thermometer
<b>Reliability Test</b>		
Life Test	Appearance : No damage.	Preconditioning: Run through IR reflow for 2 times.( IPC/JEDEC J-STD-020DClassification Reflow Profiles) Temperature : 125 $\pm$ 2°C (Inductor) Applied current : rated current Duration : 1000 $\pm$ 12hrs Measured at room temperature after placing for 24 $\pm$ 2 hrs

Load Humidity	Inductance : within±10% of initial value Q : Shall not exceed the specification value. RDC : within ±15% of initial value and shall not exceed the specification value	Preconditioning: Run through IR reflow for 2 times.( IPC/JEDEC J-STD-020DClassification Reflow Profiles Humidity : 85±2 * R.H, Temperature : 85°C±2°C Duration : 1000hrs Min. with 100% rated current Measured at room temperature after placing for 24±2 hrs															
Moisture Resistance		Preconditioning: Run through IR reflow for 2 times.( IPC/JEDEC J-STD-020DClassification Reflow Profiles Profiles 1. Baked at50°C for 25hrs, measured at room temperature after placing for 4 hrs. 2. Raise temperature to 65±2°C 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25°C in 2.5hrs. 3. Raise temperature to 65±2°C 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25°C in 2.5hrs,keep at 25°C for 2 hrs then keep at -10°C for 3 hrs 4. Keep at 25°C 80-100%RH for 15min and vibrate at the frequency of 10 to 55 Hz to 10 Hz, measure at room temperature after placing for 1~2 hrs.															
Thermal shock		Preconditioning: Run through IR reflow for 2 times.( IPC/JEDEC J-STD-020DClassification Reflow Profiles Condition for 1 cycle Step1 : -40±2°C 30±5min Step2 : 25±2°C ≤0.5min Step3 : 125±2°C 30±5min Number of cycles : 500 Measured at room temperature after placing for 24±2 hrs															
Vibration		Oscillation Frequency: 10 ~ 2K ~ 10Hz for 20 minutes Equipment : Vibration checker Total Amplitude:1.52mm±10% Testing Time : 12 hours(20 minutes, 12 cycles each of 3 orientations).															
Bending		Shall be mounted on a FR4 substrate of the following dimensions: >=0805 inch(2012mm):40x100x1.2mm <0805 inch(2012mm):40x100x0.8mm Bending depth: >=0805 inch(2012mm):1.2mm <0805 inch(2012mm):0.8mm duration of 10 sec.															
Shock	Appearance : No damage. Impedance : within±15% of initial value Inductance : within±10% of initial value Q : Shall not exceed the specification value. RDC : within ±15% of initial value and shall not exceed the specification value	<table border="1"> <thead> <tr> <th>Type</th> <th>Peak value (g's)</th> <th>Normal duration (D) (ms)</th> <th>Wave form</th> <th>Velocity change (Vi)/ft/sec</th> </tr> </thead> <tbody> <tr> <td>SMD</td> <td>50</td> <td>11</td> <td>Half-sine</td> <td>11.3</td> </tr> <tr> <td>Lead</td> <td>50</td> <td>11</td> <td>Half-sine</td> <td>11.3</td> </tr> </tbody> </table>	Type	Peak value (g's)	Normal duration (D) (ms)	Wave form	Velocity change (Vi)/ft/sec	SMD	50	11	Half-sine	11.3	Lead	50	11	Half-sine	11.3
Type	Peak value (g's)	Normal duration (D) (ms)	Wave form	Velocity change (Vi)/ft/sec													
SMD	50	11	Half-sine	11.3													
Lead	50	11	Half-sine	11.3													
Solder ability	More than 95% of the terminal electrode should be covered with solder.	Preheat: 150°C,60sec.. Solder: Sn96.5% Ag3% Cu0.5% Temperature: 245±5°C ◦ Flux for lead free: Rosin. 9.5% ◦ Dip time: 4±1sec ◦ Depth: completely cover the termination															
Resistance to Soldering Heat		Depth: completely cover the termination <table border="1"> <thead> <tr> <th>Temperature(°C)</th> <th>Time(s)</th> <th>Temperature ramp/immersion and emersion rate</th> <th>Number of heat cycles</th> </tr> </thead> <tbody> <tr> <td>260 ±5 (solder temp)</td> <td>10 ±1</td> <td>25mm/s ±6 mm/s</td> <td>1</td> </tr> </tbody> </table>	Temperature(°C)	Time(s)	Temperature ramp/immersion and emersion rate	Number of heat cycles	260 ±5 (solder temp)	10 ±1	25mm/s ±6 mm/s	1							
Temperature(°C)	Time(s)	Temperature ramp/immersion and emersion rate	Number of heat cycles														
260 ±5 (solder temp)	10 ±1	25mm/s ±6 mm/s	1														
Terminal Strength	Appearance : No damage. Impedance : within±15% of initial value Inductance : within±10% of initial value Q : Shall not exceed the specification value. RDC : within ±15% of initial value and shall not exceed the specification value e	Preconditioning: Run through IR reflow for 2 times.( IPC/JEDEC J-STD-020DClassification Reflow Profiles With the component mounted on a PCB with the device to be tested, apply a force(>0805:1kg , <=0805:0.5kg)to the side of a device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to apply a shock to the component being tested. 															

Note : When there are questions concerning measurement result : measurement shall be made after 48 ± 2 hours of recovery under the standard condition.